|  |  |
| --- | --- |
| **THE SOCIETY FOR****POST-MEDIEVAL ARCHAEOLOGY****The Paul Courtney Congress Bursary Award Application Form** | SPMA |

**About the award:**

The Society makes an annual award, in memory of Paul Courtney, to enable attendance at the Society’s annual congress on post-medieval archaeology. Each award proposal will be subject to a maximum of £250, and the total fund available in a single application round is £250. The award may be split between one or two applicants.

Council will prioritise the following groups: first time attendees, students, those on low-income and minority applicants (all self-defined). Applicants can be located in any part of the world. Council will not favour presentation over attendance and there is no restriction on age. Applicants need not be members of the Society. The award can be spent on registration/travel/hotel costs/childcare costs. Payments will be made to applicants before the congress.

**Reports:**

Awardees will be required to write a short report on their experience at the congress for the Society website and newsletter within three months of the congress.

**The deadline for receipt of applications in 2024 is March 20.**

 **How to apply:**

Applicants should complete this form, outlining why attendance would be useful, any expected outcomes from attendance, and a breakdown of expected costs. Once completed, this form should be submitted to the Society’s Prize Co-ordinator at prizes@spma.org.uk. Successful applicants will be informed by March 31.

|  |
| --- |
| Title and full name:  |
| Address: |
| Email address:  |
| Name of congress: |
| Total funds requested from SPMA:  |
| This box should be used to outline the details of the proposed travel, outlining why attendance would be useful, any expected outcomes from attendance, and a **detailed** breakdown of expected costs in no more than 500 words.  |

I hereby agree that I will supply a report on your experience at the congress for the Society website and newsletter within three months of the congress.

Applicant’s signature \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ Date\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_